AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Ling CHEN et al.					Docket No. AM-5209.D2		
Application No. 10/693,775	Filing Date 10/24/03	Examiner T. Nguyen	Customer N	lo. (Group Art Unit 2813	Confirmation No. 1973	
Invertion: TANTALUM BARRIER LAYER FOR COPPER METALLIZATION							
COMMISSIONER FOR PATENTS:							
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.							
CLAIMS AS AMENDED							
	CLAIMS REMAINING	HIGHEST #	NUMBER EXTRA		RATE	ADDITIONAL	
	AFTER AMENDMENT	PREV. PAID FOR	CLAIMS PRESENT			FEE	
TOTAL CLAIMS	42 -	41. =	1	X	\$18.00	\$18.00	
INDEP. CLAIMS	10 -	8 =	2	X	\$86.00	\$172.00	
Multiple Dependent Claims (check if applicable)							
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$190.00	
 No additional fee is required for amendment. □ Please charge Deposit Account No. in the amount of ☒ A check in the amount of \$190.00 to cover the filing fee is enclosed. ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0636 ☒ Any additional filing fees required under 37 C.F.R. 1.16. ☒ Any patent application processing fees under 37 CFR 1.17. Charles S. Guenzer, Reg. No. 30,640 [I certify that this document and fee is being deposited on]							
Mailing Address:	Mailing Address: Applied Materials, Inc. July 21, 2004 with the U.S. Postal Service as fi class mail under 37 C.F.R. 1.8 and is addressed to the service as fine to the service as fi						
Commissioner for Patents, P.O. Box 1450. Alexandria, VA							

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